

This listing of claims replaces all prior versions, and listings, of claims in this application.

**Listing of Claims:**

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1 (Canceled) A probe for a probe card characterized in that the same has a structure where either nickel plating or nickel alloy plating is applied to the surface of a core material made of either palladium alloy or beryllium copper alloy.

A<sup>1</sup>  
2. (Currently Amended) A probe for a probe card characterized in that the same has a structure where either nickel plating or nickel alloy plating is applied to the surface of a core material made of [either] palladium alloy [or beryllium copper alloy] and then a wire drawing operation with a wire drawing die is performed.

3. (Canceled) A probe for a probe card according to claim 1 characterized in that a gold plating is applied to the upper-most surface of said probe.

4. (Currently Amended) [A] The probe for a probe card according to claim 2 characterized in that a gold plating is further applied to the upper-most surface of said probe after said wire drawing operation is performed.

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5. (Newly Added) The probe for a probe card according to claim 2, wherein the probe can be applied for performing an inspection of an IC chip having an inter-electrode pitch size of 100  $\mu\text{m}$ .

6. (Newly Added) The probe for a probe card according to claim 2, wherein the probe is 65  $\mu\text{m}$  in diameter.

7. (Newly Added) The probe for a probe card according to claim 6, whereby positional displacement in respect to the IC chip electrode is minimized.

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8. (Newly Added) The probe for a probe card according to claim 2, wherein thickness of the nickel plating or nickel alloy plating is 3 – 15  $\mu\text{m}$ .

9. (Newly Added) The probe for a probe card according to claim 4, wherein thickness of the gold plating is about 0.2 – 1.0  $\mu\text{m}$ .

10. (Newly Added) A probe for a probe card characterized in that the same has a structure where either nickel plating or nickel alloy plating is applied to the surface of a core material made of beryllium copper alloy and then a wire drawing operation with a wire drawing die is performed.

11. (Newly Added) The probe for a probe card according to claim 10, wherein the probe can be applied for performing an inspection of an IC chip having an inter-electrode pitch size of 100  $\mu\text{m}$ .

12. (Newly Added) The probe for a probe card according to claim 10, wherein the probe is 65  $\mu\text{m}$  in diameter.

13. (Newly Added) The probe for a probe card according to claim 10, whereby positional displacement in respect to the IC chip electrode is minimized.

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14. (Newly Added) The probe for a probe card according to claim 10, wherein thickness of the nickel plating or nickel alloy plating is 3 – 15  $\mu\text{m}$ .

15. (Newly Added) The probe for a probe card according to claim 10 characterized in that a gold plating is further applied to the upper-most surface of said probe after said wire drawing operation is performed.

16. (Newly Added) The probe for a probe card according to claim 15, wherein thickness of the gold plating is about 0.2 – 1.0  $\mu\text{m}$ .

17. (Newly Added) A probe for a probe card characterized in that the same has a structure where either cold wire drawn nickel plating or cold wire drawn nickel alloy plating is applied to the surface of a core material made of palladium alloy.

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